

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	[STRUCTURE OF A SUBSTRATE FOR A HIGH DENSITY SEMICONDUCTOR PACKAGE]
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Application Number :

Date :

First Named Applicant: Mr. Chung W. Ho

Attorney Docket Number: 10517-US-PA

TOTAL FEE AUTHORIZED \$ 424

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as small entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	2001	375	375
Subtotal For Basic Filing Fees: \$ 375			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 21	1	2202	9	9
Independent Claims : 1	0	2201	42	0
Subtotal For Extra Claims Fees: \$ 9				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Credit account number: 1007

Expiration Date (YYYYMMDD): 2005-12-31

Authorized name: YEH, WEN-HUNG

Billing address: 99999